

STM32WL3 - QFN48 - 4-Layers - External PA

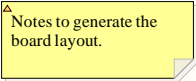
MB2158

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- Sheet 6 : FEM module

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.



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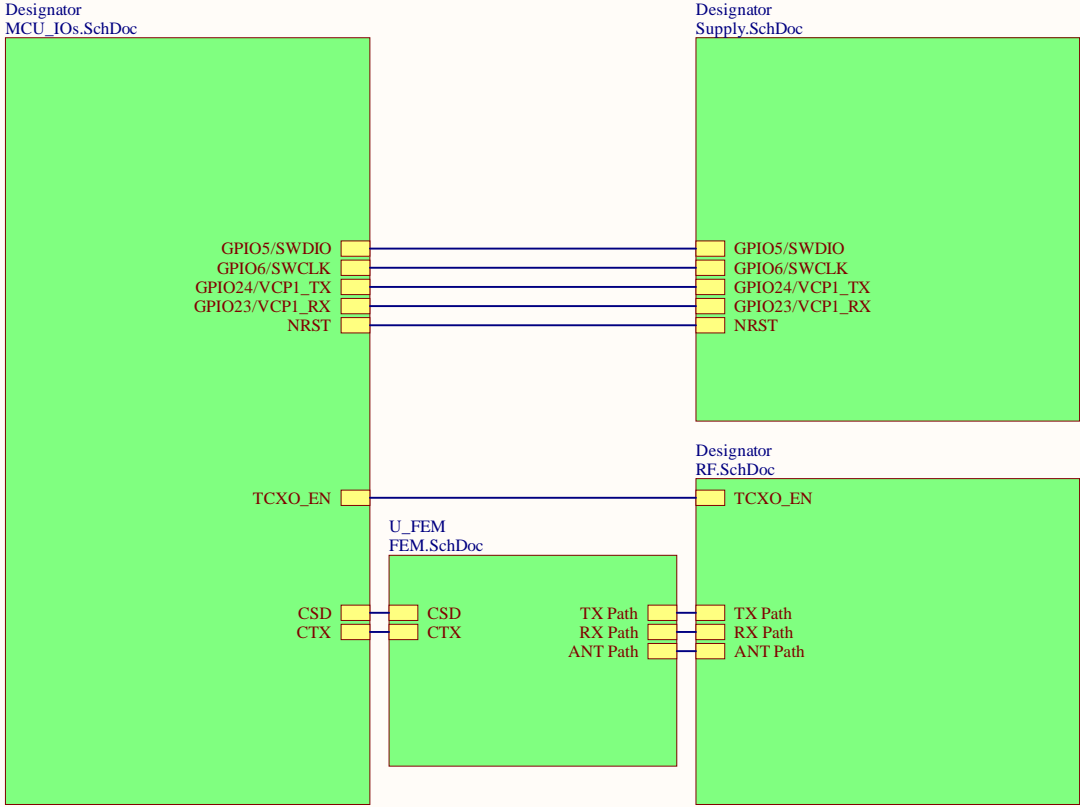
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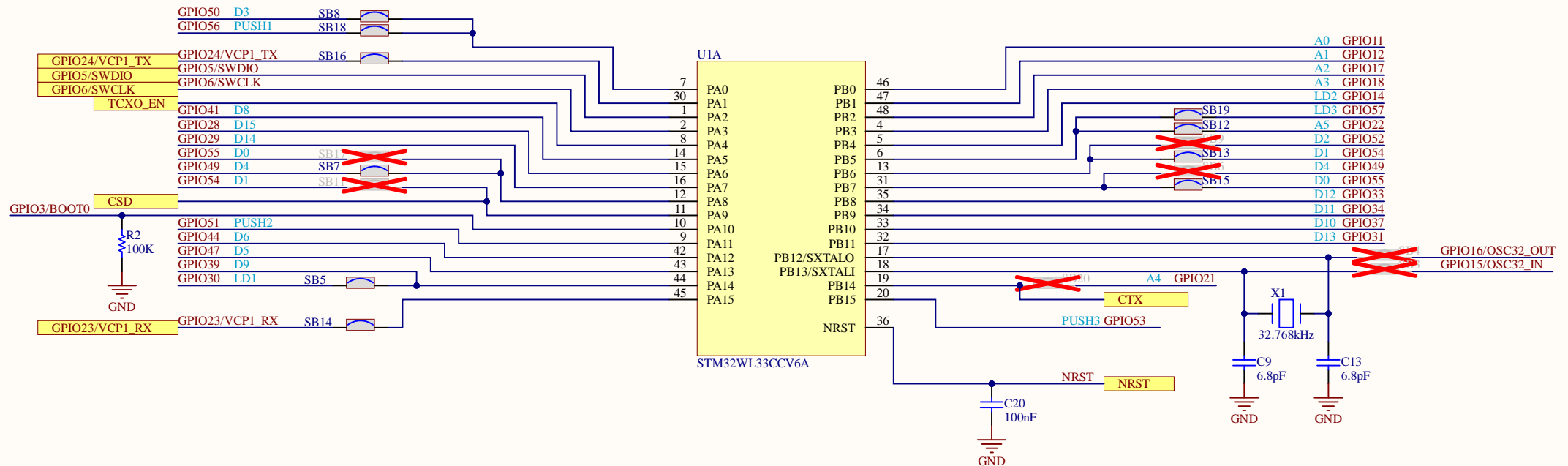
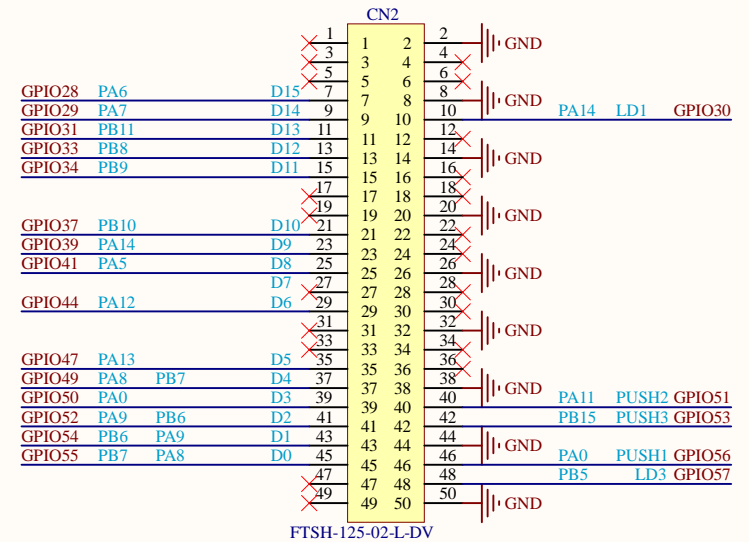
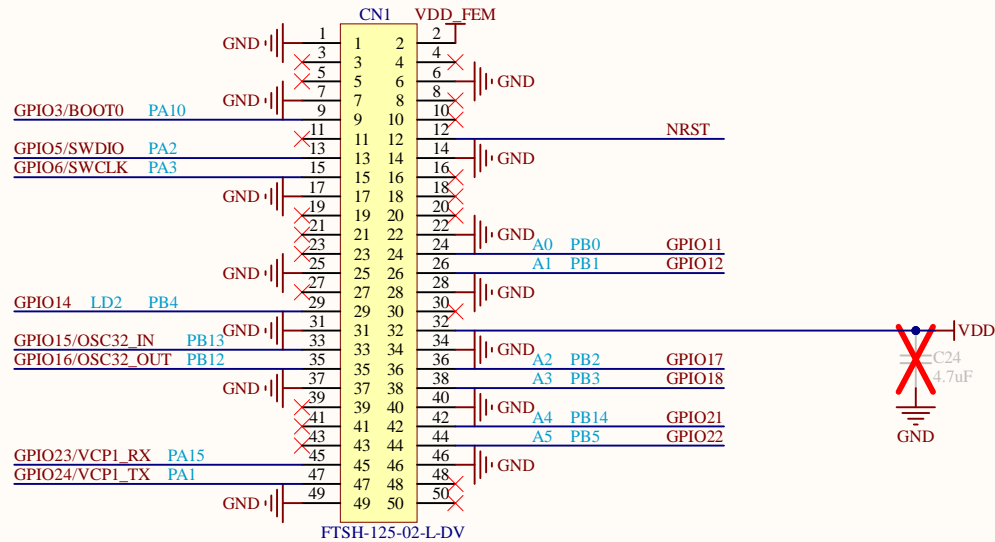
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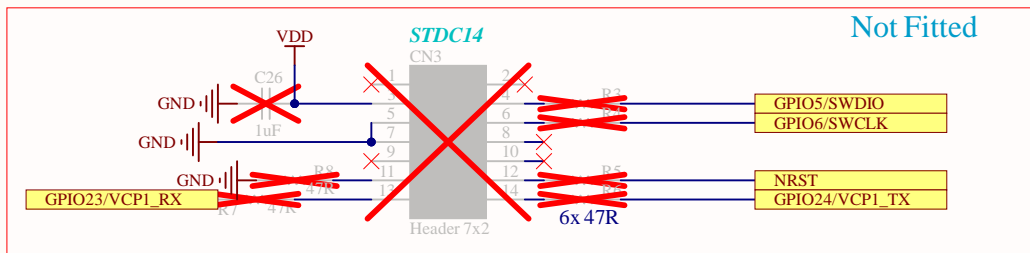
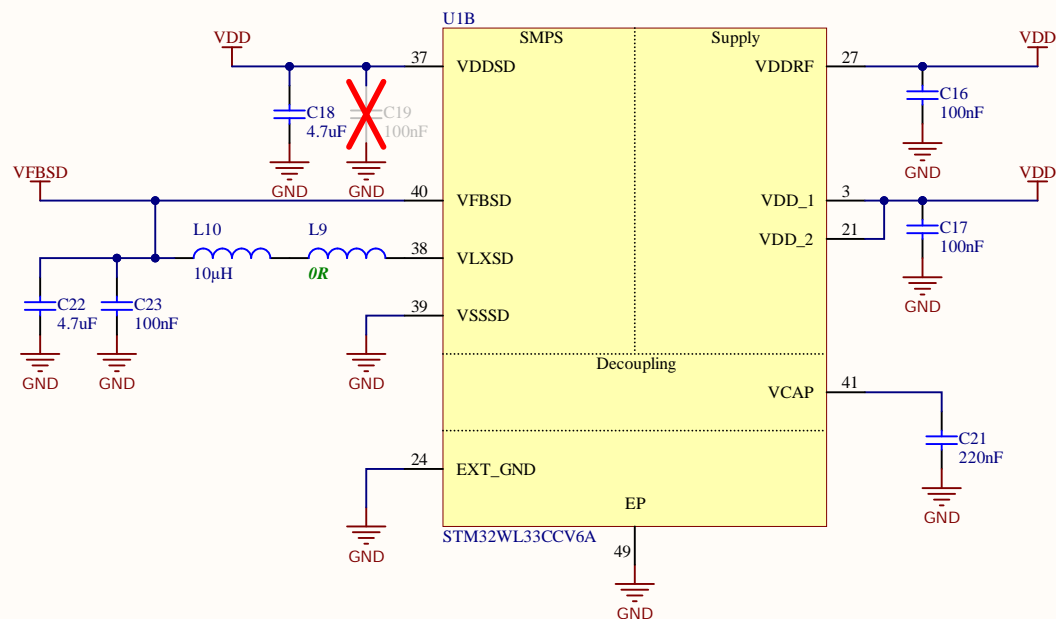


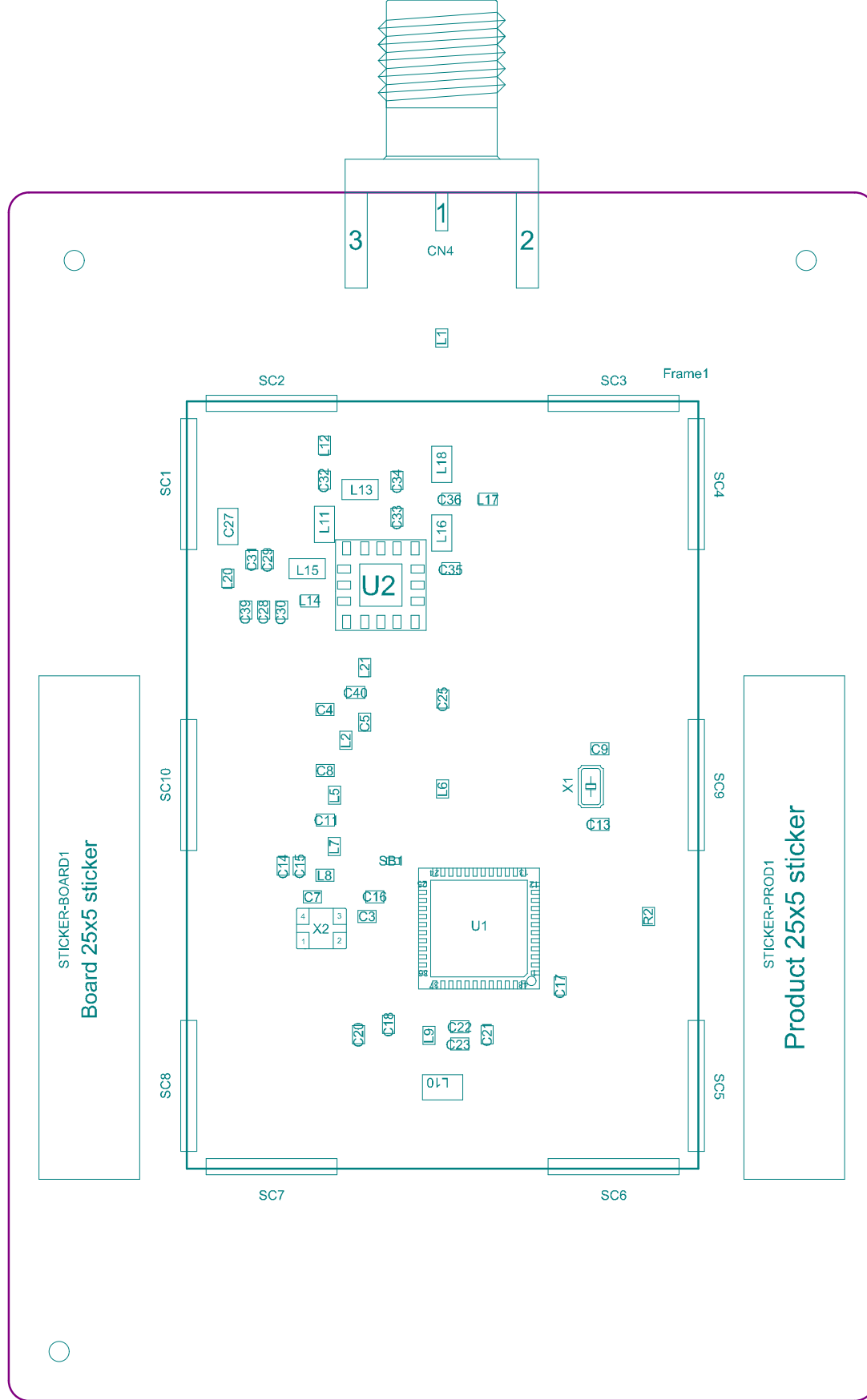
Title: Project Overview		
Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Variant: 169_27dBm		
Revision: A-01		Reference: MB2158
Size: A4	Date: 12/02/2024	Sheet: 1 of 6




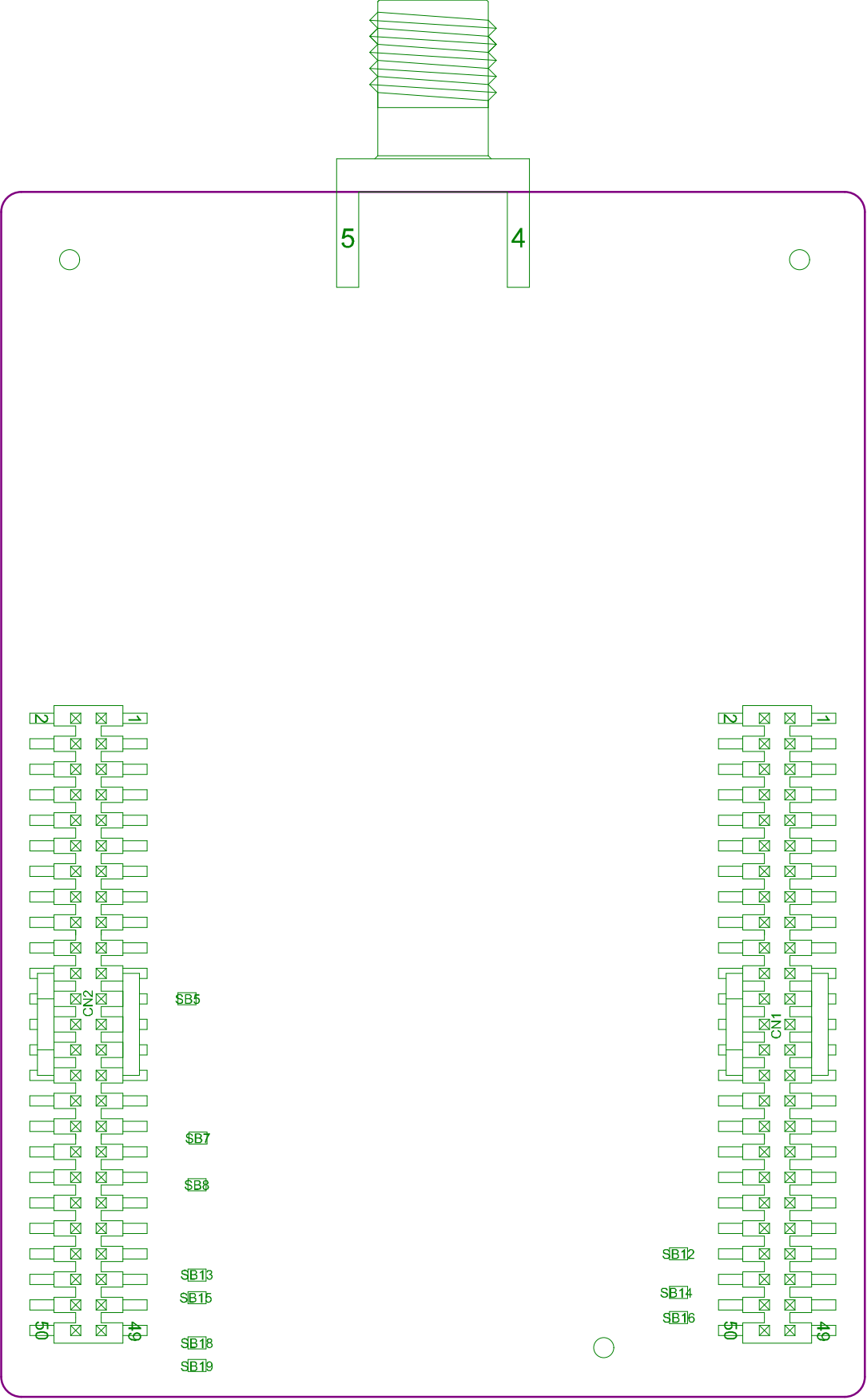








Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: M14-Top Assembly	Gerber: .GM14	
Variant: 169_27dBm	Ref: MB2158	
Date: 12/02/2024	Rev: A	



Project: STM32WL3 - QFN48 - 4-Layers - External PA

Layer: M15-Bottom Assembly

Gerber:.GM15

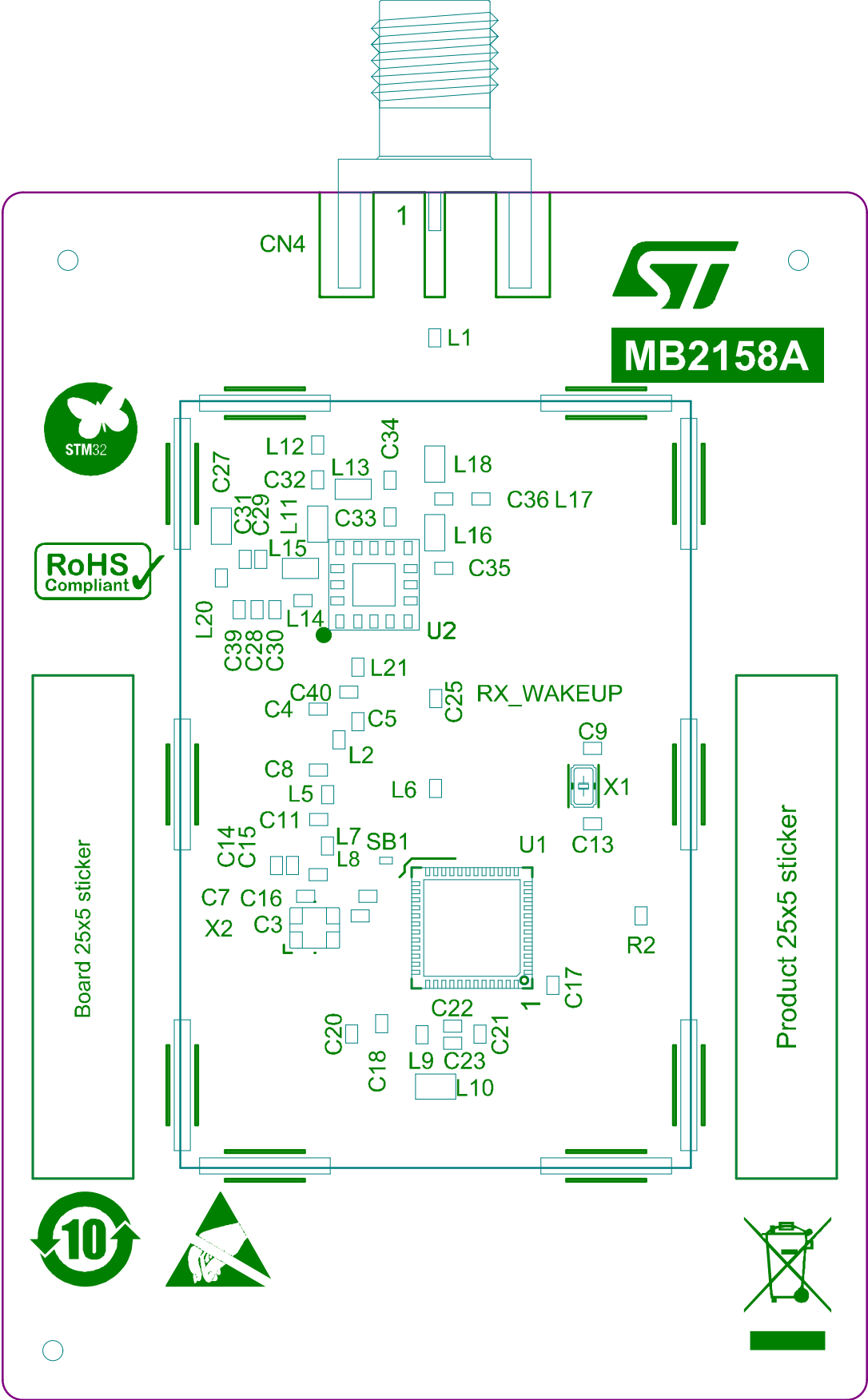
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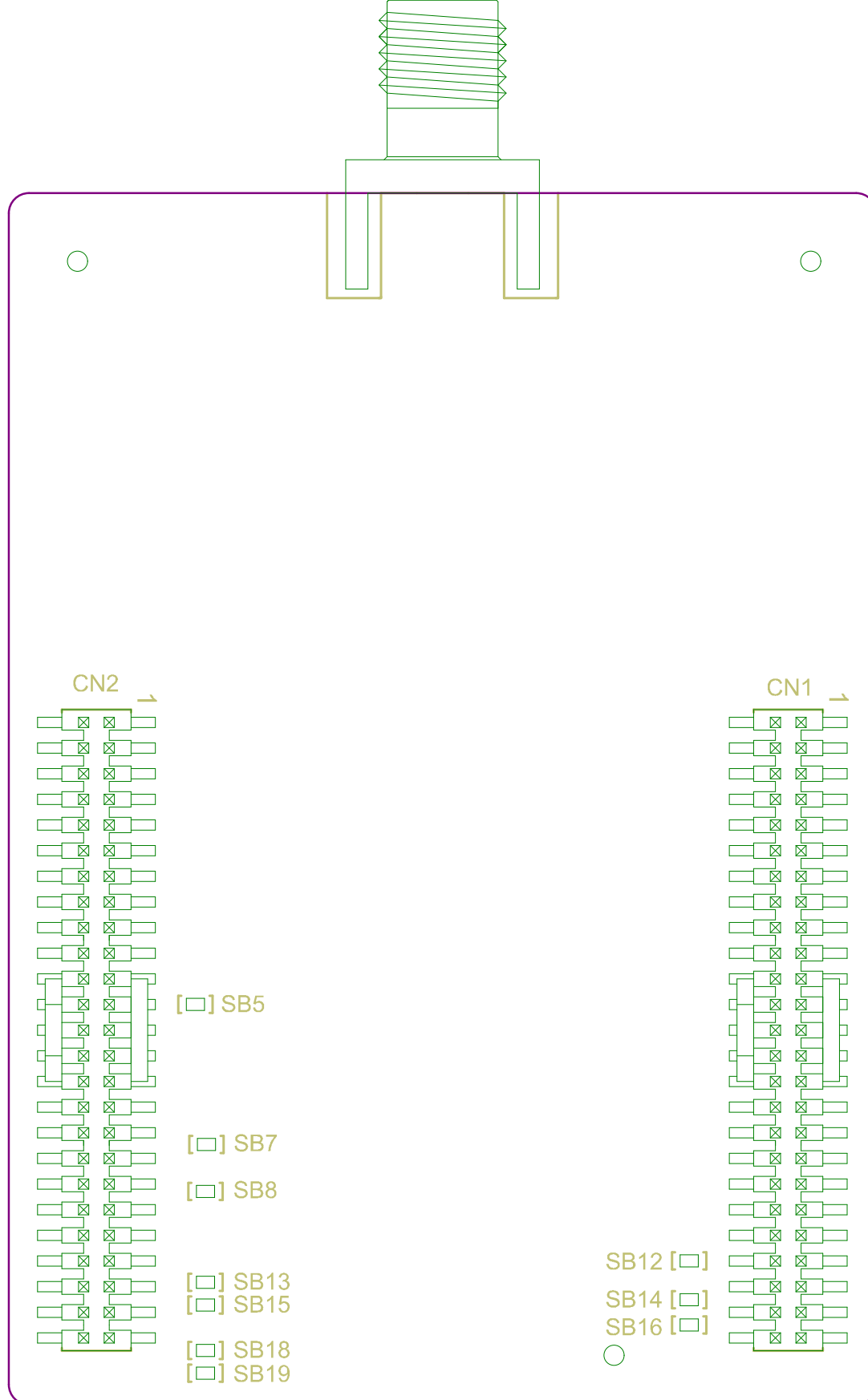
Ref: MB2158

Date: 12/02/2024

Rev: A







Bottom Overlay

.GBO